CPI1008J2R2R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

Inductance(uH)

2.5

2.0

1.5

1.0

0.5

0.0

0.1

0.3

0.5

0.7

DC BIAS Current (A)

0.9

Inductance(uH)

A 2.50 [.098] ± 0.20[.008]

B 2.00 [.079] ± 0.20[.008]

 $0.90 [.035] \pm 0.10[.004]$

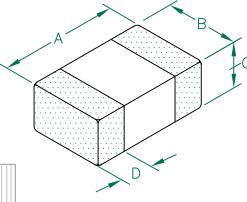
D 0.60 [.024] ± 0.20[.008]

10

Ls vs Frequency

100

Frequency (MHz)
Ls vs DC BIAS Current



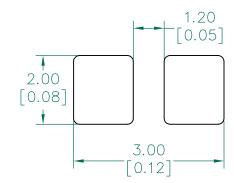


ELECTRICAL CHARACTERISTICS:										
	L (μΗ) @ 1MHz ± 20%	DCR ($\frac{\Omega}{2}$) ± 25%	l (Max)							
Nom	2.20	0.1700								
Min	1.76	0.1275								
Max	2.64	0.2125	1300mA							

NOTES: UNLESS OTHERWISE SPECIFIED

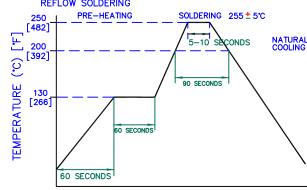
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering. add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS REFLOW SOLDERING





1.000

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Lair	rd					
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С	UPDATE PAD DIMENSION ROHS	07/08/14	QU	CF1100002N2N-10		" "				
В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCAL	E: N	TS	SHEET:		
Α	ORIGINAL DRAFT	03/01/11	QU	, ,	TOOL		13			
REV	DESCRIPTION	DATE	INT			• •	-	1	of 1	